

Automotive Electronics Council

Component Technical Committee

Agenda

(subject to change)

**2023 - Third European
Automotive Electronics
Reliability Workshop**

October 4 & 5

Toulouse, France
Diagora Congress Center

Wednesday October 4, 2023

8.00 AM - 8.30 AM Registration					
Opening		8.30 AM - 9.00 AM	Welcome and Introduction	Rene Rongen	NXP semiconductors
Technical Session 1 Mission Profiles 9.00 AM - 10.30 AM	T1.1	9.00 AM - 9.30 AM	Extended Mission Profile Model for Automotive Applications	Horst Lewitschnig	Infineon Technologies
	T1.2	9.30 AM - 10.00 AM	High Temperature Aging of New Package Technologies for Extended of Mission Profile	Romuald Roucou	NXP semiconductors
	T1.3	10.00AM - 10.30 AM	Applying ZVEI Robustness Validation process to automotive mission profiles :lessons learned from joint Tier one and supplier projects.	Allan Webber / Friedrich Schroeder	Texas Instruments / Robert Bosch GmbH
10.30 AM - 11.00 AM Break					
Workshop 1 AEC-Q100 11.00 AM - 11.45 AM	W1	11.00 AM - 11.45 AM	Status AEC-Q100 Failure Mechanism Based Stress Test Qualification For Integrated Circuits	Ulrich Abelein	Infineon Technologies
Workshop 2 CDCQ 11.45 AM - 12.30 AM	W2	11.45 AM - 12.30 AM	Status CDCQ AEC Q100 Certificate of Design and Construction (CDC) Template Certificate	Mike Buzinski	Microchip
12.30 AM - 1.30 PM Lunch					
Technical Session 2 Mission Profiles / Zero Defects 1.30 PM - 3.00 PM	T2.1	1.30 PM - 2.00 PM	Inline Defect Part Average Testing (I-PAT): Program Update and HVM Case Studies	David W. Price	KLA Corporation
	T2.2	2.00 PM - 2.30 PM	Where are we today on the journey to Zero Defects?	Carsten Ohlhoff	Continental Automotive Technologies
	T2.3	2.30 PM - 3.00 PM	ST approach to Qualify Phase Change Memory in Automotive applications.	Riccardo Cea	STMicroelectronics
Workshop 3 AEC-Q006 3.00 PM - 4.00 PM	W3	3.00 PM - 4.00 PM	Status AEC-Q006 Qualification Requirements for Components using Copper (Cu) Wire Interconnects	Ulrich Abelein	Infineon Technologies
4.00 PM - 4.30 PM Break					
Workshop 4 AEC-Q200 4.30 PM - 5.15 PM	W4	4.30 PM - 5.15 PM	Status AEC-Q200 Stress Test Qualification For Passive Components	Christoph Raible	TDK
Workshop 5 AEC-103-002 5.15 PM - 5.45 PM	W5	5.15 PM - 5.45 PM	Status AEC-Q103-002 Failure Mechanism Based Stress Test Qualification for Micro Electro-Mechanical System (MEMS) Pressure Sensor Devices	Mykola Blyznyuk	Melexis
5.45 PM - 6.00 PM Wrap-up Day 1					

Thursday October 5, 2023

Workshop 6 AEC-Q004 / AEC-Q104 8.30 PM - 9.00 PM	W6	8.30 PM - 9.00 PM	Status AEC-Q004 Automotive Zero Defects Framework Status AEC-Q104 Failure Mechanism Based Stress Test Qualification For Multichip Modules (MCM) In Automotive Applications	Rene Rongen	NXP Semiconductors
Technical Session 3 OEM / WBG / BLR 9.00 AM - 10.30 AM	T3.1	9.00 AM - 9.30 AM	Strengths and Weaknesses of the AEC Framework	Oliver Senfleben	BMW Group
	T3.2	9.30 AM - 10.00 AM	Accelerated Dynamic Stress Tests for SiC devices: Challenges and Solutions for an Industrial Implementation	Carlos Jiménez Guerra	Onsemi
	T3.3	10.00AM - 10.30 AM	Best Practices for Statistical Analysis of Board-Level Reliability Test Data	Ben Albiston	Micron Technology, Inc
10.30 AM - 11.00 AM Break					
Workshop 7 Wide Band Gap (WBG) 11.00 AM - 12.00 PM	W7	11.00 AM - 12.00 PM	Status WBG Initiatives AEC (Task force to draft Standard) and JEDEC JC-70	Massimiliano Regardi / Laurent Guillot	Infineon Technologies / STMicroelectronics
Workshop 8 Q101 12.00 PM - 12.30PM	W8	12.00 PM - 12.30PM	Status AEC-Q101 Failure Mechanism Based Stress Test Qualification For Discrete Semiconductors	Bassel Atala	STMicroelectronics
12.30 AM - 1.30 PM Lunch					
Technical Session 4 Board Level Reliability (BLR) 1.30 PM - 3.00 PM	T4.1	1.30 PM - 2.00 PM	Let's Test the Test: Study on Solderability	Jennifer Rieder	AMS Osram
	T4.2	2.00 PM - 2.30 PM	Characteristics and Acceleration according to Solder Ball Composition with Bi added related to Board Level Reliability	Jinsoo Bae	Samsung Electronics
	T4.3	2.30 PM - 3.00 PM	Performance and Reliability of Resonant Multilayer Ceramic Capacitors (MLCCs) in On-Board Chargers (OBCs)	Maawad Makdessi	YAGEO - KEMET Electronics Corporation
Workshop 9 AEC-Q007 3.00 PM - 4.00 PM	W9	3.00 PM - 4.00 PM	Status AEC-Q007 (incl. AEC-Q007-001/2) Failure Mechanism Based Testing Guidelines for Components Mounted To A Printed Board (BLR)	Thomas Koschmieder	Veoneer
4.00 PM - 4.30 PM Break					
Workshop 10 AEC-Q102-003 4.30 PM - 5.15 PM	W10	4.30 PM - 5.15 PM	Status AEC-Q102-003 Optoelectronic Multichip Modules (OE-MCMs)	Uwe Berger	Forvia (Hella)
Workshop 11 AEC-Q105 5.15 PM - 5.45 PM	W11	5.15 PM - 5.45 PM	Status AEC-Q105 Touch Screens and Displays	Matthias Ogonda	Forvia (Hella)
5.45 PM - 6.00 PM Wrap-up and Closure					